

CLAIMS

1. A film laminate comprising a heat-resistant polymer film, a plasma CVD layer of an organic metal compound provided on at least one side of said heat-resistant polymer film, and an electrically conductive layer provided on said plasma CVD layer.
2. The film laminate as recited in claim 1, wherein said organic metal compound includes at least one member selected from the group consisting of organic silicon compounds, organic titanium compounds and organic aluminum compounds.
3. The film laminate as recited in claim 1 or 2, wherein said heat-resistant polymer film is at least one member selected from the group consisting of aromatic polyimide films, liquid crystal polyester films and aromatic polyamide films.
4. The film laminate as recited in any one of claims 1 through 3, wherein said heat-resistant polymer film is an aromatic polyimide film having a water absorption coefficient of 2 % or less and a linear expansion coefficient of  $2 \times 10^{-5}/^{\circ}\text{C}$  or less.
5. The film laminate as recited in any one of claims 1 through 4, additionally comprising a resin layer which has a thickness of 5  $\mu\text{m}$  or less, which is provided between said heat-resistant polymer layer and said plasma CVD layer and which contains a fluorinated polyimide resin or a silicone-polyimide resin.
6. The film laminate as recited in any one of claims 1 through 5, wherein said electrically conductive layer is a

copper layer formed by a sputtering method and having a thickness of 1  $\mu\text{m}$  or less.

7. The film laminate as recited in any one of claims 1  
5 through 5, wherein said electrically conductive layer is a two-layered copper layer having a total thickness of 20  $\mu\text{m}$  or less and composed of a copper layer formed by a sputtering method and an electrolytic copper layer formed by an electrolytic plating using said copper layer as an  
10 electrode.

8. A flexible circuit board comprising a film laminate according to any one of claims 1 through 6 with said electrically conductive layer being patterned to form a  
15 circuit, and a copper plating layer provided on said circuit.

9. A flexible circuit board obtainable by a method comprising forming a photosensitive resin over said  
20 electrically conductive layer of a film laminate according to any one of claims 1 through 6, patterning said photosensitive layer to expose said electrically conductive layer, copper-plating said exposed electrically conductive layer to form a copper layer, and removing  
25 remaining photosensitive resin and said electrically conductive layer below said remaining photosensitive resin.